

GND 12

13

NC - No internal connection

GND

FEATURES

TEATORES	PW P	ACKAGE
Controlled Baseline		P VIEW)
 One Assembly Site 		
 One Test Site 		24 V _{CCB}
 One Fabrication Site 		23 NC
	A1 🛛 3	22 🛛 OE
 Extended Temperature Performance of –55°C 	A2 🛛 4	21 🛛 B1
to 125°C	A3 🛽 5	20 🛛 B2
Enhanced Diminishing Manufacturing Sources	A4 [6	19 🛛 B3
(DMS) Support	A5 [7	18 🛛 B4
Enhanced Product-Change Notification	A6 🛛 8	17 🛛 B5
Qualification Pedigree (1)	A7 🛛 9	16 🛛 B6
	A8 🛛 10	15 🛛 B7
Bidirectional Voltage Translator	GND 11	14 1 B8

- 4.5 V to 5.5 V on A Port and 2.7 V to 5.5 V on B Port
- Control Inputs V_{IH}/V_{IL} Levels Are Referenced to V_{CCA} Voltage
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)
- (1) Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

DESCRIPTION/ORDERING INFORMATION

The SN74LVCC4245A is an 8-bit (octal) noninverting bus transceiver that uses two separate power-supply rails. The A port (V_{CCA}) is dedicated to accepting a 5-V supply level, and the configurable B port, which is designed to track V_{CCB} , accepts voltages from 3 V to 5 V. This allows for translation from a 3.3-V to a 5-V environment and vice versa.

The SN74LVCC4245A is designed for asynchronous communication between data buses. The device transmits data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the device so the buses effectively are isolated. The control circuitry (DIR, \overline{OE}) is powered by V_{CCA}.

ORDERING INFORMATION⁽¹⁾

T _A	PACK	AGE ⁽²⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING		
–55 °C to 125 °C	TSSOP – PW	Reel of 2000	CLVCC4245AMPWREP	LG245A-EP		

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI Web site at www.ti.com.

(2) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



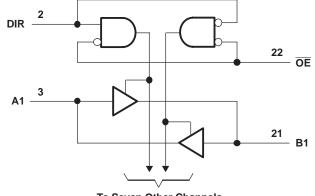
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



FUNCTION TABLE (EACH TRANSCEIVER)

INP	UTS	OPERATION
OE	DIR	OFERATION
L	L	B data to A bus
L	н	A data to B bus
н	Х	Isolation

LOGIC DIAGRAM (POSITIVE LOGIC)



To Seven Other Channels

Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V _{CCA} V _{CCB}	Supply voltage range		-0.5	6	V
		I/O ports (A port)	-0.5	V _{CCA} + 0.5	
VI	Input voltage range ⁽²⁾	I/O ports (B port)	-0.5	V _{CCB} + 0.5	V
		Except I/O ports	-0.5	V _{CCA} + 0.5	
	Output voltage range ⁽²⁾	A port	-0.5	V _{CCA} + 0.5	V
Vo		B port	-0.5	V _{CCB} + 0.5	V
I _{IK}	Input clamp current	V _I < 0 V		-50	mA
I _{OK}	Output clamp current	V _O < 0 V		-50	mA
I _O	Continuous output current			±50	mA
	Continuous current through V_{CCA} , V_{CCB} ,	or GND		±100	mA
θ_{JA}	Package thermal impedance ⁽³⁾			88	°C/W
T _{stg}	Storage temperature range		-65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) This value is limited to 6 V maximum.

(3) The package thermal impedance is calculated in accordance with JESD 51-7.



SCAS830-MARCH 2007

Recommended Operating Conditions⁽¹⁾

		V _{CCA}	V _{CCB}	MIN	NOM	MAX	UNIT	
V _{CCA}	Supply veltage			4.5	5	5.5	V	
V _{CCB}	- Supply voltage			2.7	3.3	5.5	V	
		4.5 V	2.7 V	2				
V _{IHA}	High-level input voltage	4.3 V	3.6 V	2			V	
		5.5 V	5.5 V	2				
		4.5 V	2.7 V	2				
V _{IHB}	High-level input voltage	4.3 V	3.6 V	2			V	
		5.5 V	5.5 V	3.85				
		4 5 \/	2.7 V			0.8	.8	
V _{ILA}	Low-level input voltage	4.5 V	3.6 V			0.8	V	
		5.5 V	5.5 V			0.8		
		4.5 V	2.7 V			0.8		
V _{ILB}	Low-level input voltage	4.3 V	3.6 V			0.8	V	
		5.5 V	5.5 V			1.65		
	High-level input voltage (control pins) (referenced to V_{CCA})	4 5 \/	2.7 V	2			V	
VIH		4.5 V	3.6 V	2				
		5.5 V	5.5 V	2				
		4.5 V	2.7 V			0.8		
V _{IL}	Low-level input voltage (control pins) (referenced to V_{CCA})	4.5 V	3.6 V			0.8	V	
		5.5 V	5.5 V			0.8		
V _{IA}	Input voltage			0		V_{CCA}	V	
V _{IB}	Input voltage			0		V _{CCB}	V	
V _{OA}	Output voltage			0		V_{CCA}	V	
V _{OB}	Output voltage			0		V_{CCB}	V	
I _{OHA}	High-level output current	4.5 V	3 V			-24	mA	
I _{OHB}	High-level output current	4.5 V	2.7 V to 4.5 V			-24	mA	
I _{OLA}	Low-level output current	4.5 V	3 V			24	mA	
I _{OLB}	Low-level output current	4.5 V	2.7 V to 4.5 V			24	mA	
T _A	Operating free-air temperature			-55		125	°C	

(1) All unused inputs of the device must be held at the associated V_{CC} or GND to ensure proper device operation. See the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



SCAS830-MARCH 2007

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{CCA}	V _{CCB}	MIN	TYP	MAX	UNIT
N/		I _{OH} = -100 μA			4.4	4.49		V
V _{OHA}		$I_{OH} = -24 \text{ mA}$	4.5 V	3 V	3.76	4.25		v
		I _{OH} = -100 μA	4.5 V	3 V	2.9	2.99		
		1	4.5.1	2.7 V	2.2	2.5		
V _{OHB}		$I_{OH} = -12 \text{ mA}$	4.5 V	3 V	2.46	2.85		
				2.7 V	2.1	2.3		V
		$I_{OH} = -24 \text{ mA}$	4.5 V	3 V	2.25	2.65		
				4.5 V	3.76	4.25		
V		I _{OL} = 100 μA	4.5 V	3 V			0.1	V
V _{OLA}		I _{OL} = 24 mA	4.5 V	3 V		0.21	0.44	
		I _{OL} = 100 μA	100 μA 4.5 V				0.1	
V _{OLB}		$I_{OL} = 12 \text{ mA}$	4.5 V	2.7 V		0.11	0.44	
				2.7 V		0.22	0.5	V
		I _{OL} = 24 mA	4.5 V	3 V		0.21	0.44	
	-			4.5 V		0.18	0.44	
I _I Control inputs	Control inputs	$V_{I} = V_{CCA}$ or GND	5.5 V	3.6 V		±0.1	±1	μA
· · · · · ·			0.0 V	5.5 V		±0.1	±1	μΑ
I _{OZ} ⁽¹⁾	A or B port	$V_{O} = V_{CCA/B}$ or GND, $V_{I} = V_{IL}$ or V_{IH}	5.5 V	3.6 V		±0.5	±5	μΑ
		$A_n = V_{CC} \text{ or } GND$	5.5 V	Open		8	80	
I _{CCA}	B to A	I_{O} (A port) = 0, $B_{n} = V_{CCB}$ or GND	5.5 V	3.6 V		8	80	μA
			0.0 1	5.5 V		8	80	
I _{CCB}	A to B	$A_n = V_{CCA}$ or GND, I_O (B port) = 0	5.5 V	3.6 V		5	50	μA
			0.0 1	5.5 V		8	80	<i>μ</i>
	A port	$V_{I} = V_{CCA} - 2.1$ V, Other inputs at V _{CCA} or GND, OE at GND and DIR at V _{CCA}	5.5 V	5.5 V		1.35	1.5	
$\Delta I_{CCA}^{(2)}$	OE	V_{I} = V_{CCA} – 2.1 V, Other inputs at V_{CCA} or GND, DIR at V_{CCA} or GND	5.5 V	5.5 V		1	1.5	mA
	DIR	$V_{I} = V_{CCA} - 2.1$ V, Other inputs at V_{CCA} or GND, OE at V_{CCA} or GND	5.5 V	3.6 V		1	1.5	
$\Delta I_{CCB}^{(2)}$	B port	$V_{I} = V_{CCB} - 0.6$ V, Other inputs at V_{CCB} or GND, OE at GND and DIR at GND	5.5 V	3.6 V		0.35	0.5	mA
C _i	Control inputs	$V_{I} = V_{CCA}$ or GND	Open	Open		5		pF
C _{io}	A or B port	$V_{O} = V_{CCA/B}$ or GND	5 V	3.3 V		11		pF

For I/O ports, the parameter I_{OZ} includes the input leakage current.
 This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or the associated V_{CC}.

TEXAS INSTRUMENTS www.ti.com

Switching Characteristics

over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1 through Figure 4)

PARAMETER	FROM		V _{CCA} = 5 V ± V _{CCB} = 5 V ±	± 0.5 V, ± 0.5 V	V _{CCA} = 5 V ± V _{CCB} = 2.7 V	UNIT		
	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX		
t _{PHL}	A	P	1	7.1	1	7		
t _{PLH}	~	В	1	6	1	7	ns	
t _{PHL}	В	۸	1	6.8	1	6.2	20	
t _{PLH}		A	1	6.1	1	5.3	ns	
t _{PZL}	ŌĒ	А	1	9	1	9	20	
t _{PZH}	UE	A	1	8.3	1	8	ns	
t _{PZL}	OE	В	1	8.2	1	10	20	
t _{PZH}	UE	D	1	8.1	1	10.2	ns	
t _{PLZ}		۸	1	5.5	1	5.9		
t _{PHZ}	ŌĒ	A	1	5.7	1	5.9	ns	
t _{PLZ}	OE	В	1	6.4	1	6.4	20	
t _{PHZ}	UE	D	1	7.8	1	8.9	ns	

Operating Characteristics

 $V_{CCA} = 5 \text{ V}, V_{CCB} = 3.3 \text{ V}, T_A = 25 \text{ }^{\circ}\text{C}$

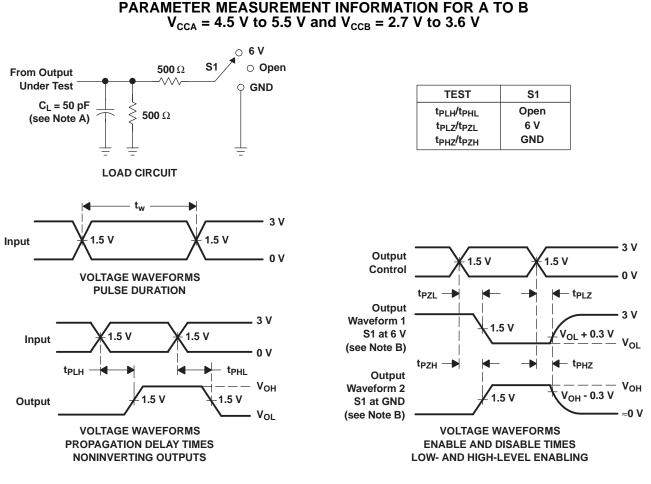
	PARAMETER	TEST C	ONDITIONS	TYP	UNIT	
<u> </u>	Dower discipation conscitance per transaciver	Outputs enabled	C 0	f 10 MU-	20	~ [
C _{pd}	Power dissipation capacitance per transceiver	Outputs disabled	$C_{L} = 0,$	f = 10 MHz	6.5	рF

Power-Up Considerations⁽¹⁾

TI level-translation devices offer an opportunity for successful mixed-voltage signal design. A proper power-up sequence should always be followed to avoid excessive supply current, bus contention, oscillations, or other anomalies caused by improperly biased device pins. Take the following precautions to guard against such power-up problems:

- 1. Connect ground before any supply voltage is applied.
- 2. Power up the control side of the device (V_{CCA} for all four of these devices).
- 3. Tie \overline{OE} to V_{CCA} with a pullup resistor so that it ramps with V_{CCA}.
- Depending on the direction of the data path, DIR can be high or low. If DIR high is needed (A data to B bus), ramp it with V_{CCA}. Otherwise, keep DIR low.
- (1) See the TI application report, *Texas Instruments Voltage-Level-Translation Devices*, literature number SCEA021.





Texas

STRUMENTS www.ti.com

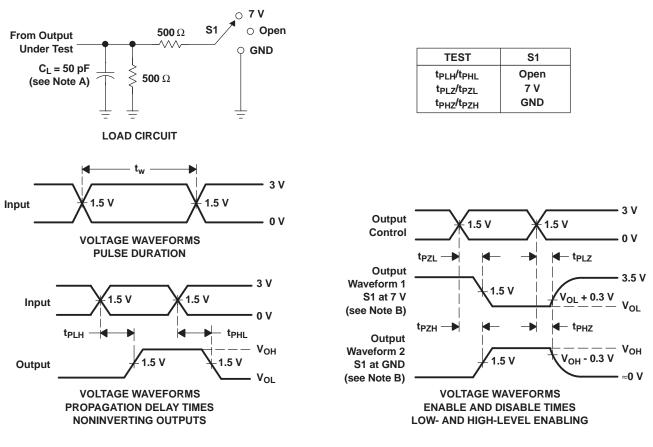
- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_Q = 50 Ω , t_f \leq 2.5 ns, t_f \leq 2.5 ns.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



SCAS830-MARCH 2007

PARAMETER MEASUREMENT INFORMATION FOR A TO B $V_{CCA} = 4.5$ V to 5.5 V and $V_{CCB} = 3.6$ V to 5.5 V

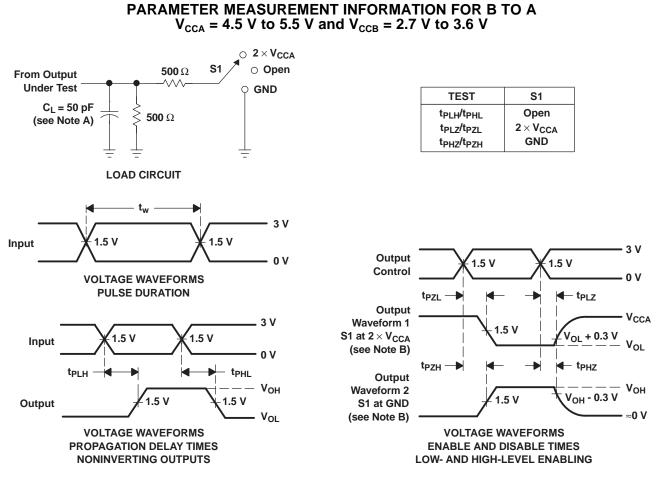


- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f \leq 2.5 ns, t_f \leq 2.5 ns.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. All parameters and waveforms are not applicable to all devices.

Figure 2. Load Circuit and Voltage Waveforms



SCAS830-MARCH 2007



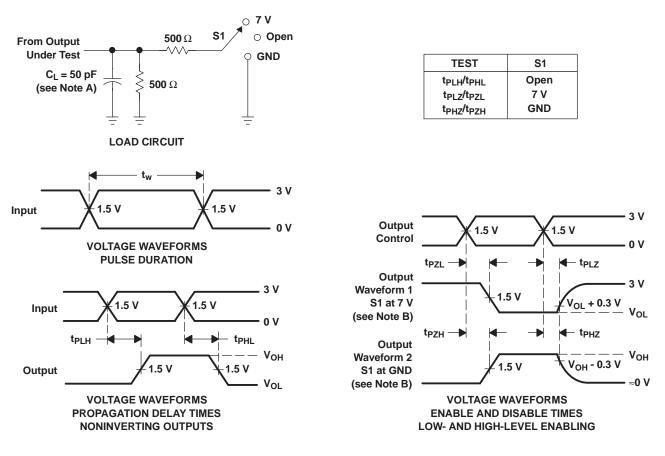
- NOTES: A. CL includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_r \leq 2.5 ns, t_f \leq 2.5 ns.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. All parameters and waveforms are not applicable to all devices.

Figure 3. Load Circuit and Voltage Waveforms



SCAS830-MARCH 2007

PARAMETER MEASUREMENT INFORMATION FOR B TO A $V_{CCA} = 4.5$ V to 5.5 V and $V_{CCB} = 3.6$ V to 5.5 V



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_Q = 50 Ω , t_r \leq 2.5 ns, t_f \leq 2.5 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 4. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
CLVCC4245AMPWREP	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CLVCC4245AMPWREPG4	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/06658-01XE	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN74LVCC4245A-EP :

Catalog: SN74LVCC4245A

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



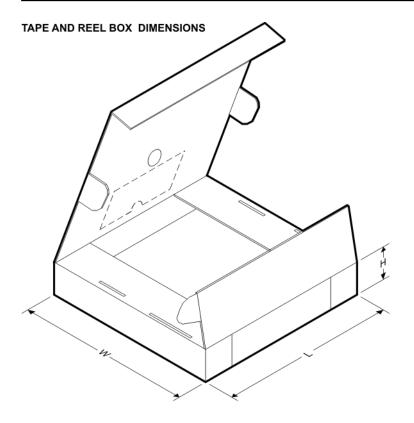
*All dimensions are nominal	
-----------------------------	--

Device		Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CLVCC4245AMPWREP	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1



PACKAGE MATERIALS INFORMATION

26-Jul-2008



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CLVCC4245AMPWREP	TSSOP	PW	24	2000	346.0	346.0	33.0

MECHANICAL DATA

MTSS001C - JANUARY 1995 - REVISED FEBRUARY 1999

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Clocks and Timers	www.ti.com/clocks	Digital Control	www.ti.com/digitalcontrol
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
RFID	www.ti-rfid.com	Telephony	www.ti.com/telephony
RF/IF and ZigBee® Solutions	www.ti.com/lprf	Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2008, Texas Instruments Incorporated